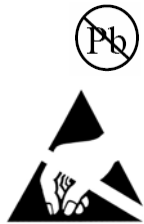


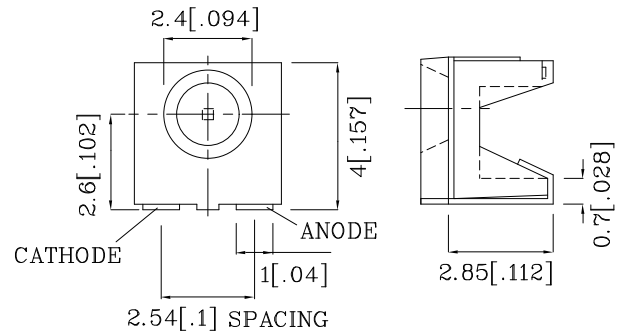
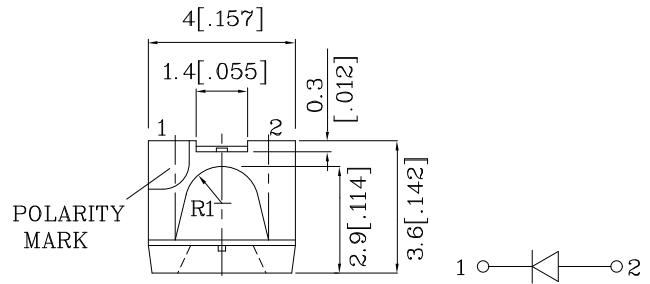
PRELIMINARY SPEC

Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE : 500PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)		M2BB (InGaN)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	100	mA
Power Dissipation	P _T	111	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V

Operating Characteristics (TA=25°C)		M2BB (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V _F	3.2	V
Forward Voltage (Max.) (I _F =20mA)	V _F	3.7	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λ _P	458	nm
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λ _D	465	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	22	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	110	pF

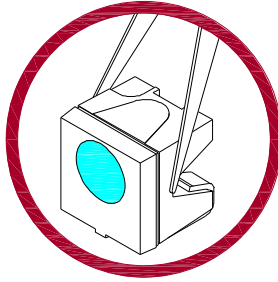
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λ _P	Viewing Angle 2 θ 1/2
				min.	typ.		
ZM2BB67S	Blue	InGaN	Water Clear	110	278	458	120°
Published Date : FEB 27,2008				Drawing No :SDSA6298		V1 Checked : B.L.LIU P.1/5	

Handling Precautions

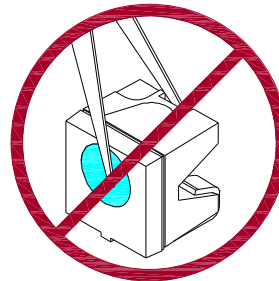
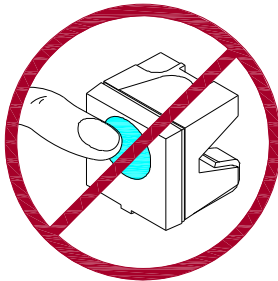
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

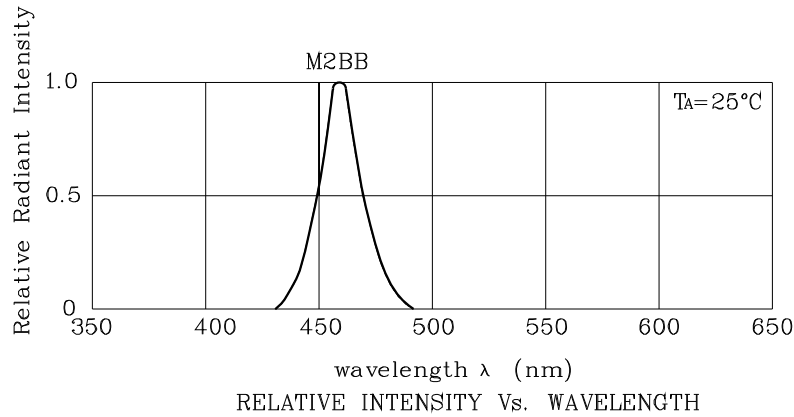
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

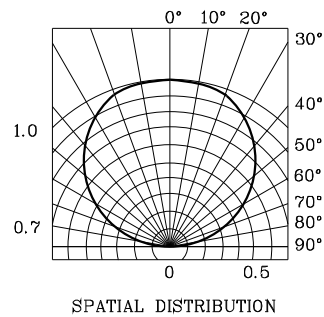
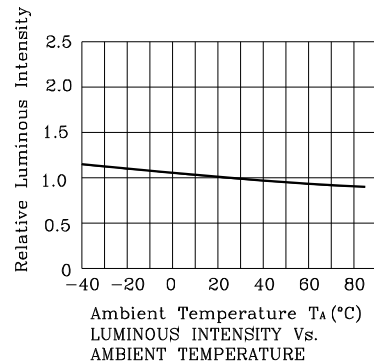
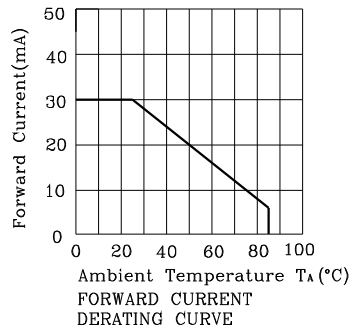
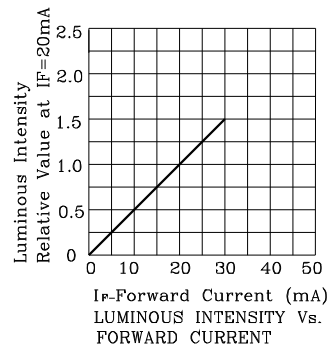
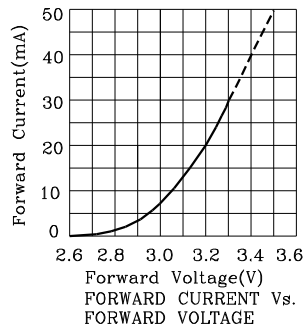


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

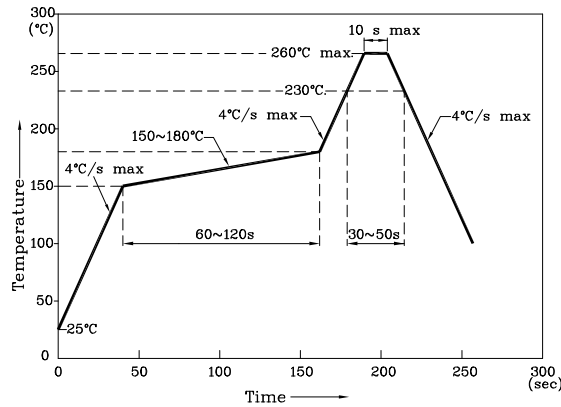




❖ M2BB



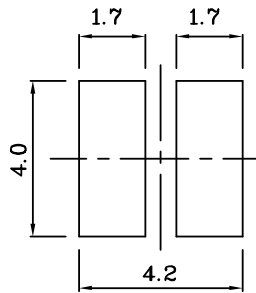
Reflow Soldering Profile For Lead-free SMT Process.



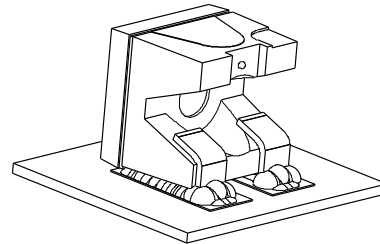
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

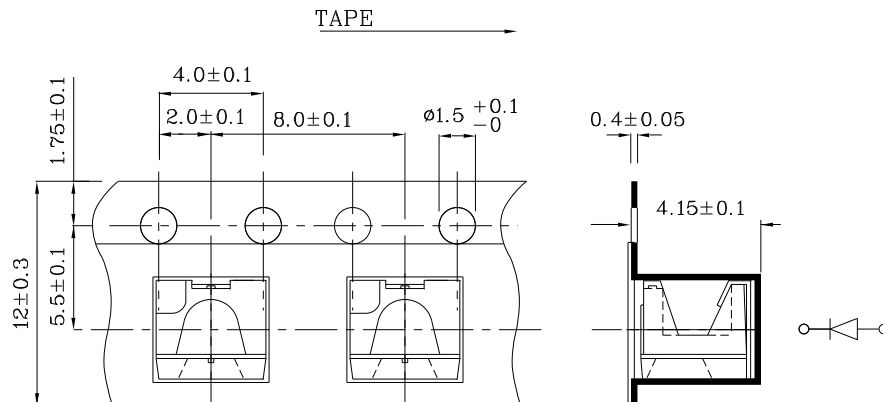
❖ Recommended Soldering Pattern
(Units : mm;Tolerance:± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

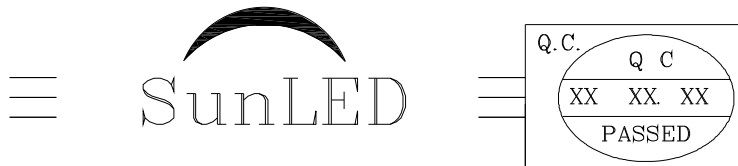
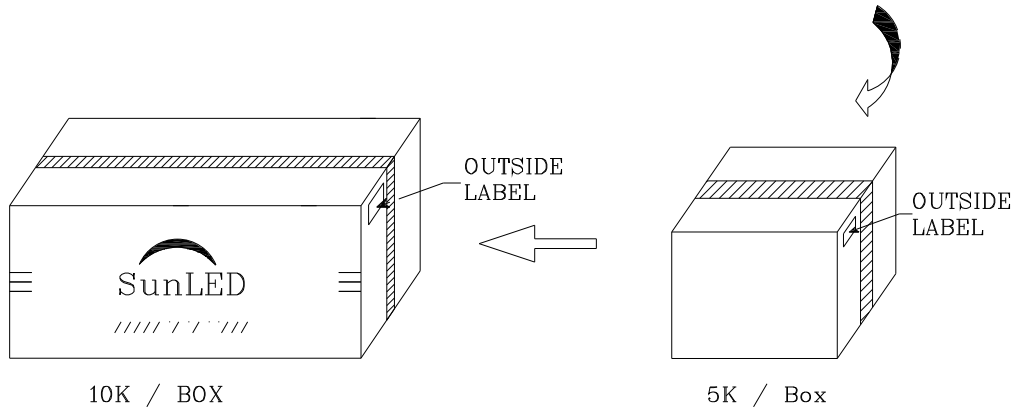
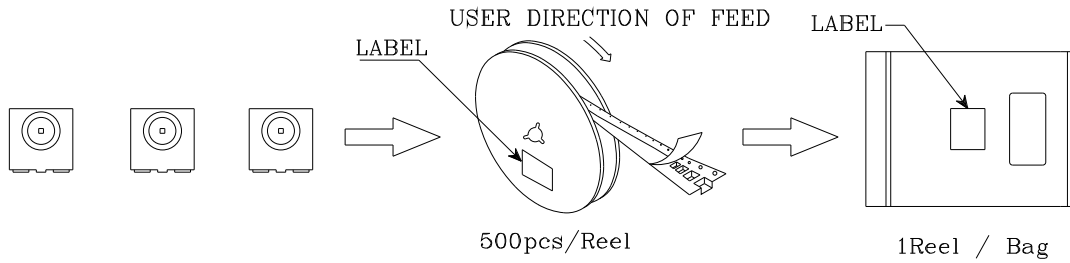
If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

ZM2BB67S



P/NO : Zxx67x	
QTY : 500 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	